

1. General description

Ultrafast power diode in a SOD142 (2-lead TO247) plastic package.

2. Features and benefits

- Fast switching
- Very low on-state loss
- Low leakage current
- Low thermal resistance

3. Applications

- Active PFC in air conditioner
- S.M.P.S Power Factor Correction (PFC)
- Half-bridge / full-bridge switched-mode power supplies

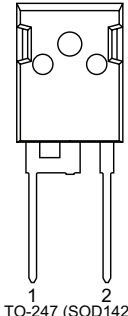
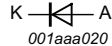
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values				Unit
Absolute maximum rating							
V _{RRM}	repetitive peak reverse voltage		600				V
I _{F(AV)}	average forward current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 129 °C; Fig. 1 ; Fig. 2 ; Fig. 3	30				A
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _{mb} ≤ 129 °C; square-wave pulse	60				A
I _{FSM}	non-repetitive peak forward current	t _p = 10 ms; T _{j(init)} = 25 °C; sine-wave pulse; Fig. 4	290				A
		t _p = 8.3 ms; T _{j(init)} = 25 °C; sine-wave pulse;	330				A
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 30 A; T _j = 25 °C; Fig. 6		-	1.18	1.55	V
		I _F = 30 A; T _j = 150 °C; Fig. 6		-	0.98	-	V
Dynamic characteristics							
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 50 A/μs; T _j = 25 °C; Fig. 7		-	42	75	ns
		I _F = 30 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7		-	65	-	ns
		I _F = 30 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _i = 125 °C; Fig. 7		-	101	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 TO-247 (SOD142)	 001aaa020
2	A	anode		
mb	mb	mounting base; connected to cathod		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYV30W-600P	TO-247	Plastic Single-ended through-hole package; Heatsink mounted; 1 mounting hole; 2-lead TO-247	SOD142

7. Marking

Table 4. Marking codes

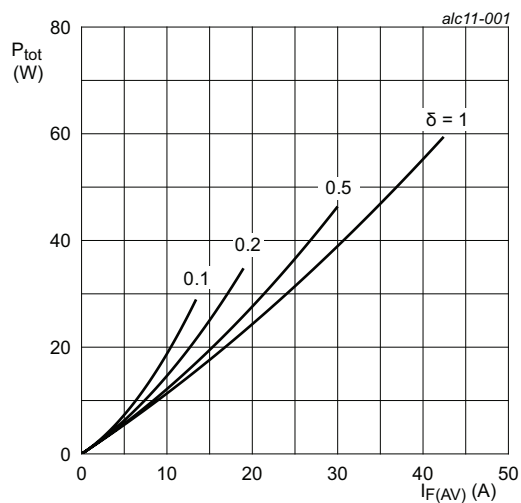
Type number	Marking codes
BYV30W-600P	BYV30W-600P

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

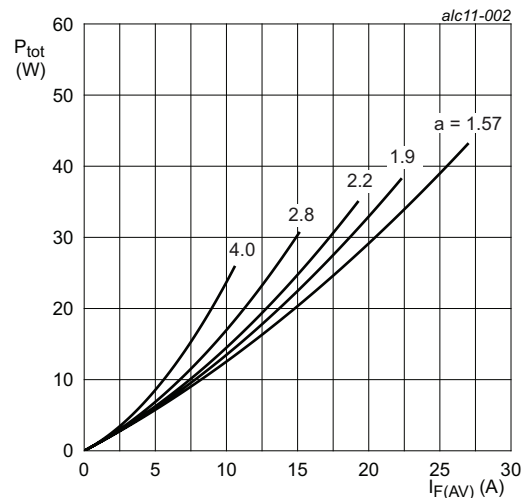
Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		600	V
V_{RWM}	crest working reverse voltage		600	V
V_R	reverse voltage	DC	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 129^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	30	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\ \mu\text{s}$; $T_{mb} \leq 129^\circ\text{C}$; square-wave pulse	60	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\ \text{ms}$; $T_{j(\text{init})} = 25^\circ\text{C}$; sine-wave pulse; Fig. 4	290	A
		$t_p = 8.3\ \text{ms}$; $T_{j(\text{init})} = 25^\circ\text{C}$; sine-wave pulse;	330	A
T_{stg}	storage temperature		-55 to 175	$^\circ\text{C}$
T_j	junction temperature		175	$^\circ\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 1.051\ \text{V}; R_s = 0.0083\ \Omega$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

$$V_o = 1.051\ \text{V}; R_s = 0.0083\ \Omega$$

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

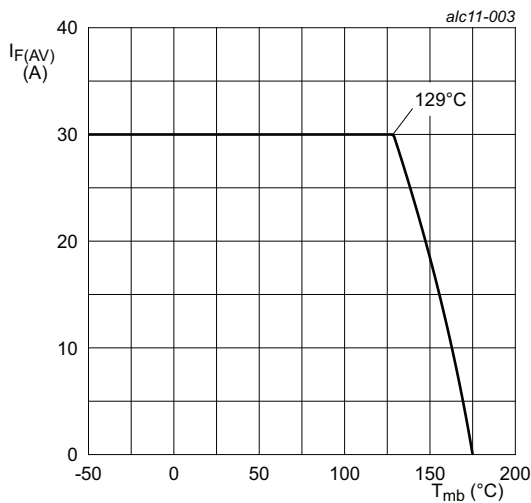


Fig. 3. Forward current as a function of mounting base temperature; maximum values

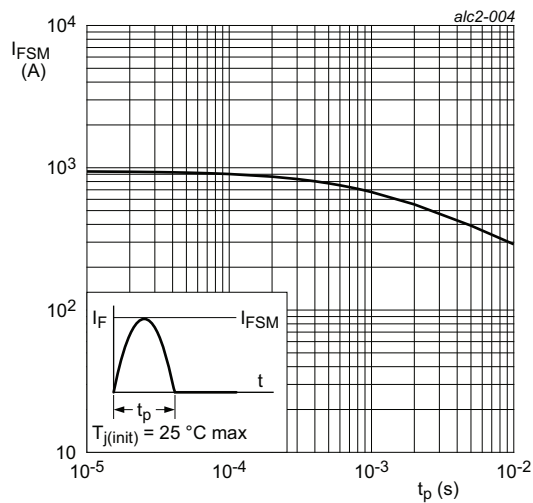


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	-	1	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	45	-	K/W

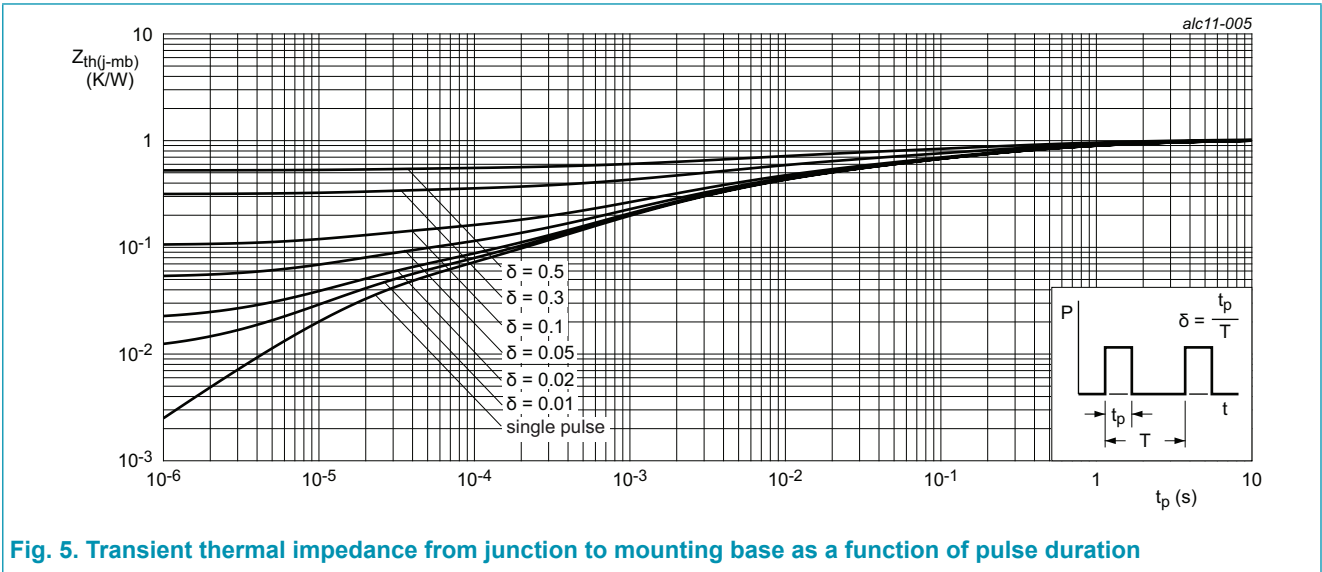
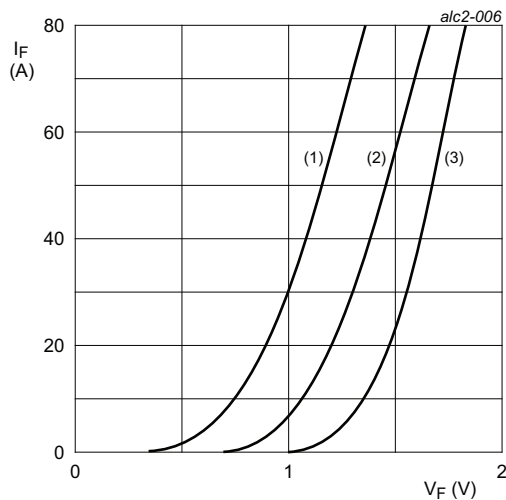


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward current	I _F = 30 A; T _j = 25 °C; Fig. 6		-	1.18	1.55	V
		I _F = 30 A; T _j = 150 °C; Fig. 6		-	0.98	-	V
I _R	reverse current	V _R = 600 V; T _j = 25 °C		-	2	10	μA
		V _R = 600 V; T _j = 125 °C		-	-	500	μA
Dynamic characteristics							
Q _r	reverse charge	I _F = 30 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7		-	272	-	nC
		I _F = 30 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7		-	775	-	nC
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 50 A/μs; T _j = 25 °C; Fig. 7		-	42	75	ns
		I _F = 30 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7		-	65	-	ns
		I _F = 30 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7		-	101	-	ns
I _{RM}	peak reverse recovery current	I _F = 30 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 25 °C; Fig. 7		-	8.4	-	A
		I _F = 30 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 125 °C; Fig. 7		-	15.2	-	A



$V_o = 1.051\text{ V}; R_s = 0.0083\text{ }\Omega$

(1) $T_j = 150\text{ °C}$; typical values

(2) $T_j = 150\text{ °C}$; maximum values

(3) $T_j = 25\text{ °C}$; maximum values

Fig. 6. Forward current as a function of forward voltage

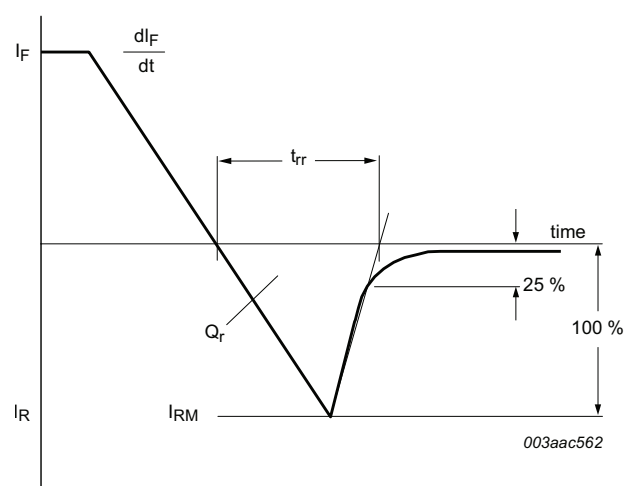


Fig. 7. Reverse recovery definitions; ramp recovery

11. Package outline

Plastic Single-ended through-hole package; Heatsink mounted; 1 mounting hole; 2-lead TO-247 SOD142

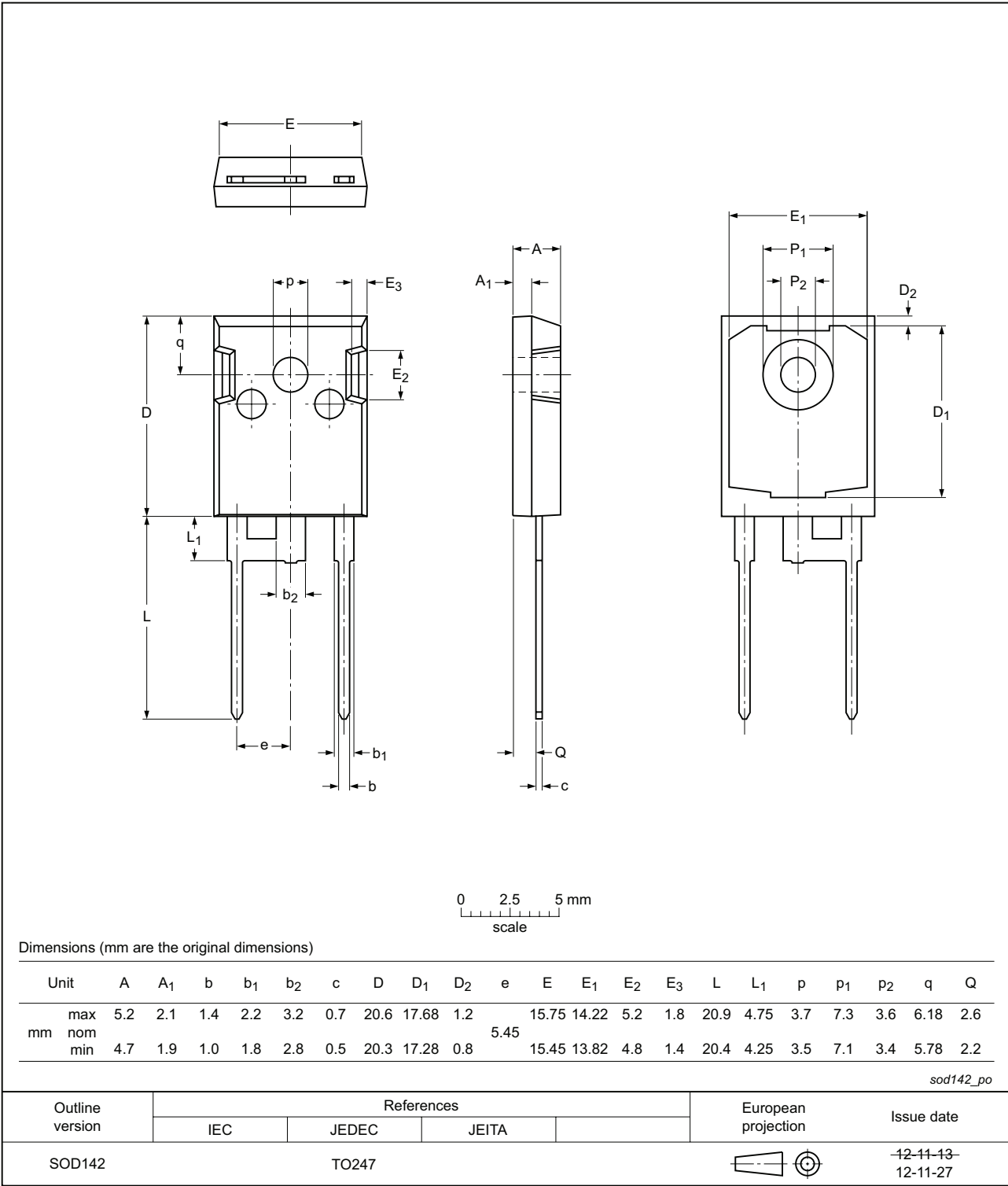


Fig. 8. Package outline SOD142

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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